

DDR4 DIMM TE Internal #: 2309409-1 Small Outline (SO), 5.2 mm [.205 in] Stack Height, Right Angle Module Orientation, 260 Position, DDR4 DIMM, SO DIMM Sockets View on TE.com >



Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM Sockets



DRAM Type: Small Outline (SO) Stack Height: 5.2 mm [.205 in] Module Orientation: Right Angle Number of Positions: 260 Centerline (Pitch): .5 mm, 3.3 mm [.02 in, .129 in]

All DDR4 SO DIMM Sockets (39)

Features

Product Type Features

Connector & Contact Terminates To

Printed Circuit Board

Cable to Pa ard

Connector System	Cable-to-Board				
DRAM Type	Small Outline (SO)				
Configuration Features					
Number of Keys	1				
Number of Rows	2				
Module Orientation	Right Angle				
Number of Positions	260				
Electrical Characteristics					
DRAM Voltage	1.2 V				
Signal Characteristics					
SGRAM Voltage	1.2 V				
Body Features					
Retention Post Location	Both Ends				
Latch Material	High Temperature Thermoplastic				
Module Key Type	Offset Left				

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Ejector Type	Locking				
Ejector Location	Both Ends				
Connector Profile	Low				
Contact Features					
Contact Current Rating (Max)	.5 A				
Memory Socket Type	Memory Card				
Contact Base Material	Copper Alloy				
PCB Contact Termination Area Plating Material	Gold Flash				
Contact Mating Area Plating Material	Gold Flash				
Termination Features					
Insertion Style	Cam-In				
Termination Method to PCB	Surface Mount				
Mechanical Attachment					
Connector Mounting Type	Board Mount				
PCB Mount Retention Type	Solder Peg				
Mating Alignment Type	Standard Keying				
PCB Mount Retention	With				

Housing Features

Housing Material	High Temperature Thermoplastic				
Housing Color	Black				
Centerline (Pitch)	.5 mm, 3.3 mm[.02 in][.129 in]				
Dimensions					
Stack Height	5.2 mm[.205 in]				
Row-to-Row Spacing	8.2 mm[.322 in]				
Usage Conditions					
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]				
Operating Temperature Range Operation/Application	-55 – 85 °C[-67 – 185 °F]				
	-55 – 85 °C[-67 – 185 °F] Power				
Operation/Application					
Operation/Application Circuit Application					
Operation/Application Circuit Application Industry Standards	Power				

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Packaging Quantity	800					
Packaging Method	Tape & Reel					
Product Compliance For compliance documentation, visit the product page on TE.com>						
EU RoHS Directive 2011/65/EU	Compliant					
EU ELV Directive 2000/53/EC	Out of Scope					
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold					
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC					
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free					
Solder Process Capability	Reflow solder capable to 260°C					

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series DDR4 DIMM

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Customers Also Bought



TE Part #1571983-9

GDH06STR04=DIP SWITCH

TE Part #2338718-3 Receptacle Assembly, 4C HI Power	TE Part #2176410-3 MPT35 6R2 1%	TE Part #2-2176331-3 CRGP 2512 680R 1%
TE	TE	
TE Part #1747981-2 Std HDMI, RA, SMT	TE Part #1888901-1 SFP+ EMI Plug	

Documents

Product Drawings DDR4 SODIMM 260P 5.2H STD

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2309409-1_1.2d_dxf.zip

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English Customer View Model ENG_CVM_CVM_2309409-1_1.3d_igs.zip English Customer View Model

ENG_CVM_CVM_2309409-1_1.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Application Specification

English